



## Material Content Data Sheet



Sales Product Name	ESD5V0S1U-02V H6327			Issued		29. August 2013		
MA#	MA000876714							
Package	PG-SC79-2-1			Weight*		1.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		18	
	noble metal	gold	7440-57-5	0.003	0.18		1791	
	inorganic material	silicon	7440-21-3	0.026	1.53	1.71	15297	17106
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		461	
	non noble metal	chromium	7440-47-3	0.002	0.14		1382	
	non noble metal	copper	7440-50-8	0.767	45.89	46.09	458928	460863
wire	non noble metal	copper	7440-50-8	0.002	0.12	0.12	1223	1223
encapsulation	organic material	carbon black	1333-86-4	0.007	0.44		4354	
	plastics	epoxy resin	-	0.124	7.40		74011	
	inorganic material	silicondioxide	60676-86-0	0.597	35.70	43.54	356996	435361
leadfinish	non noble metal	tin	7440-31-5	0.055	3.26	3.26	32644	32644
plating	noble metal	silver	7440-22-4	0.088	5.28	5.28	52803	52803
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com